

REMARKS

Claims 1 – 13 are pending and rejected.

The applicants' attorney cancels claim 13 and amends claims 1 and 12. The applicants' attorney respectfully disagrees with the examiner's rejection of claims 1 – 12 and asserts that these claims, as amended, are in condition for allowance for the reasons discussed below.

Rejection of claims 1 – 11 under 35 U.S.C. §103(a)

The applicants' attorney respectfully disagrees with the examiner's rejection of claim 1 in view of U.S. Patent 6,285,067 issued to Hyoudo *et. al.* (Hyoudo) because Hyoudo fails to disclose forming a pad on a second wafer wherein the pad projects from a surface of the second wafer.

The applicants' claim 1, as amended, recites forming a pad on a second wafer, the pad projecting from a surface of the second wafer.

For example, as shown in FIGS. 3D and 3E, and discussed in paragraphs 20 – 22 of the specification, a wafer-level package (shown but not labeled with a reference number) includes a cap wafer 203 having a gasket 201, and a base wafer 207 having a surface (also shown but not labeled with a reference number). The wafer-level package also includes a mating pad 305 that projects from the surface of the base wafer 207, and that has a surface (also shown but not labeled with a reference number) for bonding with the gasket 201 to form a hermetically sealed environment 211 (FIG. 3E). The pad 305 improves the bondability of the gasket 201 with the base wafer 207.

In contrast, Hyoudo fails to disclose forming a pad on a second wafer wherein the pad projects from a surface of the second wafer. Hyoudo discloses an electronic device (shown in FIGS. 4A and 4B but not labeled with a reference number) that includes a substrate 21 having an element mounting section 50 for mounting electronic components, and a cover member 31a fixed to the substrate 21. The substrate 21

includes a main surface 22a (not shown in FIGS. 4A and 4B, but discussed in Col. 3, lines 29 – 35 in conjunction with FIG. 4A, and shown in FIG. 2A) on which the mounting section 50 is located. The cover member 31a includes a depression 24 that corresponds to the mounting section 50 such that when the member 31a is fixed to the substrate 21, a hermetically sealed compartment is formed to protect the electronic component mounted on the substrate 21. The substrate 21 does not include a pad projecting from the main surface 22a of the substrate 21. Therefore, unlike the applicants' claimed wafer-level package, Hyoudo's electronic device does not include a pad projecting from the main surface 22a.

Claims 2 – 11 are patentable by virtue of their dependencies from claim 1.

Rejection of Claim 12 under 35 U.S.C. §102(e)

Claim 12, as amended, is patentable over Hyoudo for reasons similar to those recited in support of claim 1 over Hyoudo.

Conclusion

The applicants' attorney respectfully requests that the examiner withdraw the rejection of claims 1 – 12 in view of the amendments and remarks, and issue an allowance for these claims.

Should any additional fees be required, please charge them to Deposit Account No. 07-1897.

If the examiner believes that a phone interview would be helpful, he is respectfully requested to contact the Applicants' attorney, John Janeway, at (425) 455-5575.

DATED this 13th day of May, 2005.

Respectfully submitted,
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